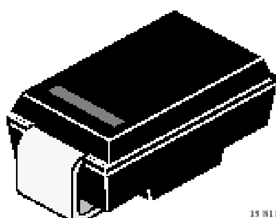
SEMICONDUCTOR
Small Signal Products

MATERIAL CONTENT LIST

PACKAGE FAMILY: **DO-214**
DATE: **2-Apr-2012**
REVISION: **9**



MATERIAL CONTENT					
Part	**Material**	**CAS N°**	**weight mg**	**% of weight**	**ppm of total weight**
Mold	SiO_2	14808-60-7	27,6	71,4%	360410
50,5%	epoxy resin	25928-94-3	10,1	26,0%	131236
	Sb_2O_3	1309-64-4	0,62	1,6%	8096
	Br	7726-95-6	0,39	1,0%	5093
	TOTAL		**38,7**		
Lead frame	Cu	7440-50-8	33,3	99,7%	434842
43,6%	Sn	7440-31-5	0,1	0,3%	1306
	and / or traces of Mg, Ag, P, Fe				
	TOTAL		**33,4**		
Terminal finish	Sn	7440-31-5	2,0	100,0%	25464
2,5%	**TOTAL**		**2,0**		
Die solder	Pb *)	7439-92-1	0,88	88,0%	11457
1,3%	Sn	7440-31-5	0,10	10,0%	1302
	Ag	7440-22-4	0,02	2,0%	261
	TOTAL		**1,0**		
Silicon	Si	7440-21-3	1,29	82,2%	16878
chip	Ag	7440-22-4	0,24	15,3%	3142
2,1%	Ni	7440-02-0	0,003	0,2%	40
	SiO_2	14808-60-7	0,036	2,3%	473
	TOTAL		**1,6**		
Total weight			**77**		

Remark: Total weight range ± 10%
*) Lead in high melting temperature type solder acc. RoHS exempted
Reflow Soldering acc. J-STD-020D
Material Analyses Reports available on request